GN01034N (Tentative)

GaAs IC

For receiving front-end amplifier of cellular phone

Features

- Low-voltage, positive power supply operation
- Low current operation
- Low noise

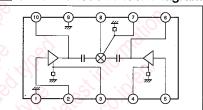
■ Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Rating	Unit	
Power supply voltage	$V_{ m DD}$	5	V	
Circuit current	I_{DD}	10	mA	
Max input power	Pin	10	dBm	
Allowable power dissipation	P_{D}	50	mW	
Operating temperature	T_{opr}	-30 to +90	$^{\circ}$	
Storage temperature	$T_{ m stg}$	-30 to +90	$^{\circ}$	

Unit: mm

- 1: GND 📡
- 6: RF Amplifier Drain
- 2: Lo Input 3: Lo Amplifier GND
- 7: Mixer Source 8: IF Output
- 4: RF Amplifier GND
- 9: GND
- 5: RF Input
- 10: Lo Amplifier Drain SSONF-10D Package

Circuit-function Block Diagram

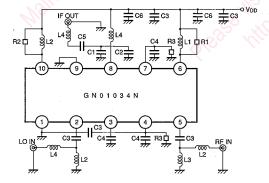


■ Electrical Characteristics $(V_{DD}=3.7V, Ta=25\pm2^{\circ}C)$

Parameter	Symbol	Test method	Condition	Min	Тур	Max	Unit
Circuit current	I_{DD}		Op die gie Ville	3.5	5.5	8	mA
Conversion gain	CG	(1)	f_{LO} =0.79GHz, P_{LO} =-15dBm f_{RF} =0.88GHz, P_{RF} =-35dBm	13	. 18		dB
Noise figure	NF	(1)	f_{LO} =0.79GHz, P_{LO} =-15dBm f_{RF} =0.88GHz, P_{RF} =-35dBm	2,	4.5	6	dB

Test method (1): Design-guaranteed value

For measurement, use the circuit shown below.



(Value of each part)

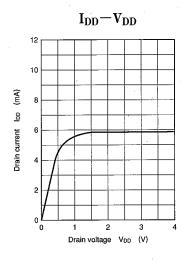
 $R1=120\,\Omega$ $\hat{L}1=15nH$ C1=4.5pF $R2=470\,\Omega$ L2=22nH C2=7pF

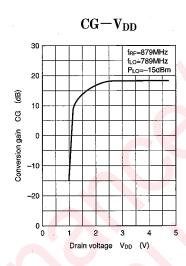
 $R3=2.2k\Omega$ L3=27nH C3=100pF L4=39nH C4=1000pF

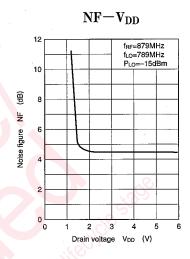
L5=390nH C5=2000pF $C6=1 \mu F$

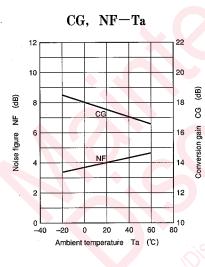
Note: This is the tentative development specification and may be changed without notice.

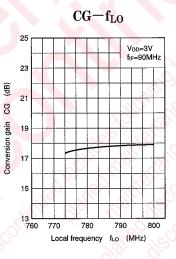
Refer to the update product specification when final design is to be established.

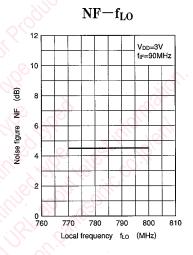


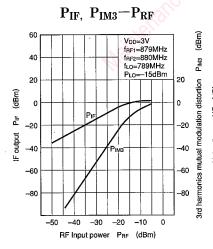


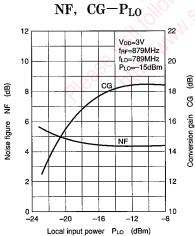












GaAs MMICs

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